

Seonho Seok

List of Publications by Year in descending order

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Version: 2024-02-01

16
papers

201
citations

1307594

7
h-index

1199594

12
g-index

16
all docs

16
docs citations

16
times ranked

135
citing authors

#	ARTICLE	IF	CITATIONS
1	A study on wafer level vacuum packaging for MEMS devices. Journal of Micromechanics and Microengineering, 2003, 13, 663-669.	2.6	120
2	Polymer-Based Biocompatible Packaging for Implantable Devices: Packaging Method, Materials, and Reliability Simulation. Micromachines, 2021, 12, 1020.	2.9	15
3	Fabrication and Modeling of Nitride Thin-Film Encapsulation Based on Anti-Adhesion-Assisted Transfer Technique and Nitride/BCB Bilayer Wrinkling. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1301-1307.	2.5	11
4	Polymer-based zero-level packaging technology for high frequency RF applications by wafer bonding/debonding technique using an anti-adhesion layer. International Journal of Precision Engineering and Manufacturing, 2012, 13, 1861-1867.	2.2	10
5	Characterization and Analysis of Metal Adhesion to Parylene Polymer Substrate Using Scotch Tape Test for Peripheral Neural Probe. Micromachines, 2020, 11, 605.	2.9	10
6	Enhancement of bonding strength of packaging based on BCB bonding for RF devices. Microsystem Technologies, 2012, 18, 2035-2039.	2.0	9
7	A theoretical and experimental study of the BCB thin-film cap zero-level package based on FEM simulations. Journal of Micromechanics and Microengineering, 2010, 20, 095010.	2.6	8
8	Overview of MEMS Packaging Technologies. Springer Series in Advanced Manufacturing, 2018, , 1-12.	0.5	6
9	A Study on Biocompatible Polymer-Based Packaging of Neural Interface for Chronic Implantation. Micromachines, 2022, 13, 516.	2.9	6
10	Experiment and analysis of the effect of BCB sealing ring flatness on BCB cap transfer packaging. Microsystem Technologies, 2021, 27, 263-268.	2.0	2
11	Scotch-tape surface wrinkling based thin-film material properties extraction. Journal of Micromechanics and Microengineering, 2022, 32, 045002.	2.6	2
12	Analysis of Thin Film Parylene-Metal-Parylene Device Based on Mechanical Tensile Strength Measurement. , 2019, , .		1
13	Editorial for the Special Issue "MEMS Packaging Technologies and 3D Integration". Micromachines, 2022, 13, 749.	2.9	1
14	FEM Modeling of Debonding of Transfer Packaging. Springer Series in Advanced Manufacturing, 2018, , 83-101.	0.5	0
15	Buckled Thin Film Cap Transfer Packaging Technology. Springer Series in Advanced Manufacturing, 2018, , 67-81.	0.5	0
16	Scotch-Tape Surface Wrinkling Based Thin-Film Material Properties Extraction. Journal of Micromechanics and Microengineering, 0, , .	2.6	0